PANEL SESSIONS

Panel I: GaAs Microwave Monolithic Integrated Circuits – MMIC

Date:	Tuesday, June 9, 1987, Noon to 1:30 pm
Location:	Gable 3 & 4
Sponsor:	MTT-6, Microwave and Millimeter Wave Integrated Circuits
Organizer:	K. Agarwal Rockwell International Corp.

Abstract:

MMIC circuits have been around for a long time. It is fair to say that GaAs MMICs have been long on performance and promise but short on delivery. The performance has been generally achieved in research labs or only in small numbers of custom fabricated parts. Efforts to produce in large quantities have been a challenge to designers and manufacturers. Purity of material and otherissues have plagued the MMICs. There has been a push from DARPA, DOD and Tri-Service to firmly establish the MMIC technology in reasonable field quantities. The panel would present their perspective of the technology and the issues involved.

Panel II: Financial Planning for Engineers, Implications of the New Tax Law on: Financial Planning, Investment Planning, Insurance Planning and Requirements for Keeping Records

Date:	Tuesday, June 9, 1987, Noon to 1:30 pm
Location:	Gable 5, 6 & 7
Sponsor:	PACE
Organizer:	R.A. Moore Westinghouse Defense & Electronics Systems Center
Speakers:	Coopers & Lybrand, Auditors for IEEE Smith Sterno, Insurance Carriers for IEEE

Abstract:

As we know, the new tax law will challenge all of us in making personal and professional financial decisions. The relationships between pensions, IRAs, 401K accounts, most investments, insurance and many other aspects of our personal and professional financial structures is changing. The speakers will provide an overview of their topics after which the floor will be open for discussion of aspects of topics on personal and professional financial planning of interest to the audience.

PANEL SESSIONS

Panel III: Applications of HEMT Devices and Circuits

Date: Wednesday, June 10, 1987, Noon to 1:30 pm

Location: Gable 5, 6 & 7

Sponsor: MTT-6, Microwave and Millimeter Wave Integrated Circuits
MTT-7, Microwave and Millimeter Wave Solid State Devices

Organizers: H.J. Kuno, Hughes Aircraft Co.
D.W. Maki, Tachonics Corp.

Panelists: Phil Smith, General Electric (Moderator)
Paul Saunier, Texas Instruments
Sandy Weinreb, National Radio Astronomy Observatory
David Wang, Hughes Aircraft Co.
Mike Sholley, TRW

Abstract:

Discussions include the application of HEMT devices and circuits for millimeter wave transmitters and receivers, for cooled, low noise microwave receivers and the commercial use of HEMTs.

Panel IV: Solutions to Problems Existing in Educating Microwave Engineers

Date: Thursday, June 11, 1987, Noon to 1:30 pm

Location: Gable 5, 6 & 7

Sponsor: Education Committee, MTT-S AdCom

Organizer: Les Besser, Besser Associates, Inc.

Speakers: Kris Agarwal, Rockwell International Corp.
Stacy Bearse, Microwave & RF Magazine
Clifford Krowne, Naval Research Laboratory
Bill Goodin, UCLA Continuing Education
Tim Healy, Santa Clara University
Ed Niehenke, Westinghouse Corp.
Fred Rosenbaum, Washington University

Abstract:

This panel discussion reviews the current educational process available to microwave engineers. Representatives from industry, government, academia and the IEEE discuss fundamental problems facing both undergraduate and practicing engineers, and will seek for a systematic way to improve basic education and to provide meaningful continuing education at various levels. Topics include a review of successful co-op programs, employee and undergraduate student motivations, economic considerations, degree oriented vs specialized courses and "computer-literacy" of microwave engineers.